



# IN-FLIGHT RECONFIGURATION WITH SYSTEM-ON-MODULE BASED ARCHITECTURES FOR SCIENCE INSTRUMENTS ON NANOSATELLITES

SSC21-VIII-08 | T. NEUBERT ET AL., ZEA-2, FORSCHUNGSZENTRUM JÜLICH GMBH, GERMANY

# FORSCHUNGSZENTRUM JÜLICH

Heritage in remote sensing instrumentation at airborne, balloon and satellites



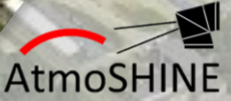
Atmospheric Physics  
IEK 7

Mechanics Engineering  
ZEA-1

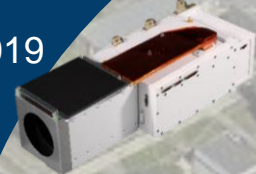
Electronics Engineering  
ZEA-2



2017



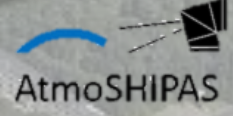
2019



2022



2023



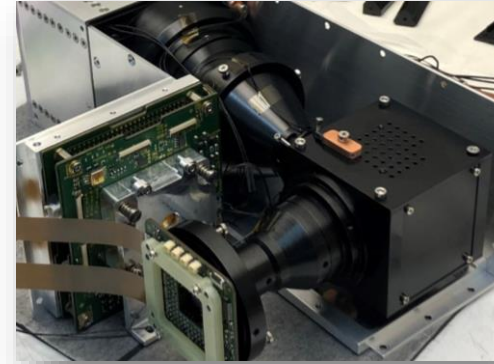
2024

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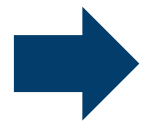
# MINIATURIZED CLIMATE RESEARCH INSTRUMENTS

## Objectives and Challenges

- standardized sublevel components available (power, communication, altitude control, deorbiting,...)
- customize **science payload electronics** needed

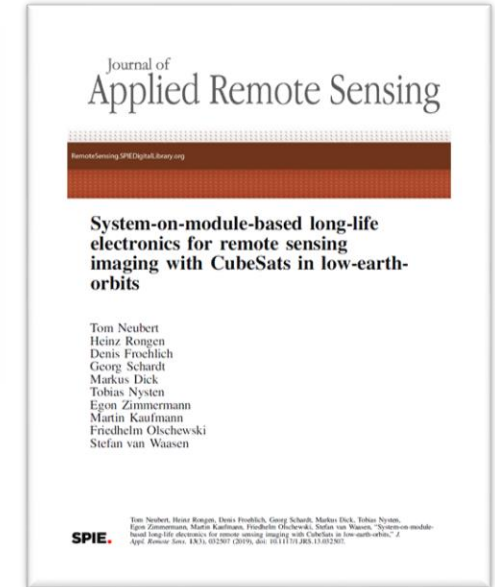


*SHI spectrometer for atmospheric temperature measurements*



**flexibility, (re)programmability, modularity, reusability**

- novel science “standardized” payload electronics based on our “system on module” approach with heritage from precursor instruments (AtmoHIT & AtmoSHINE) on sounding rocket and in space
- long-term measurements with custom mitigation techniques using COTS components
- focus is on imaging sensors in combination with integrated System-on-Chip (SoC) solutions



*SPIE-JARS 05/2019*

video

# SYSTEM-ON-MODULE APPROACH



## Features

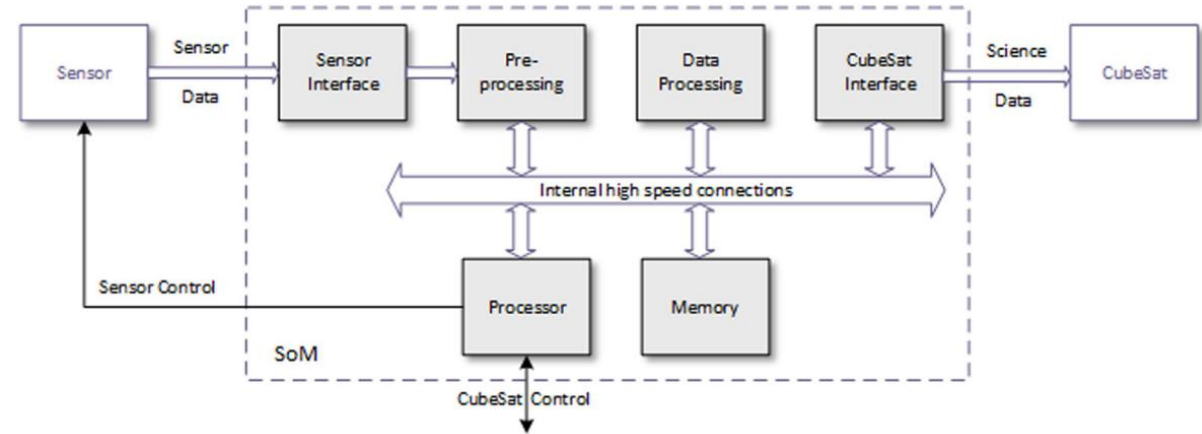
- Pin compatible modules with processing units, memory and power conversion
- Several processing capabilities (CPLD, FPGAs,  $\mu$ C, SoC, MPSoC)
- Short development time, 'low' design expertise needed (universities)

## Challenge

- Radiation environment, system reliability
- Size, power consumption, limited data bandwidth and costs

## Solution approach

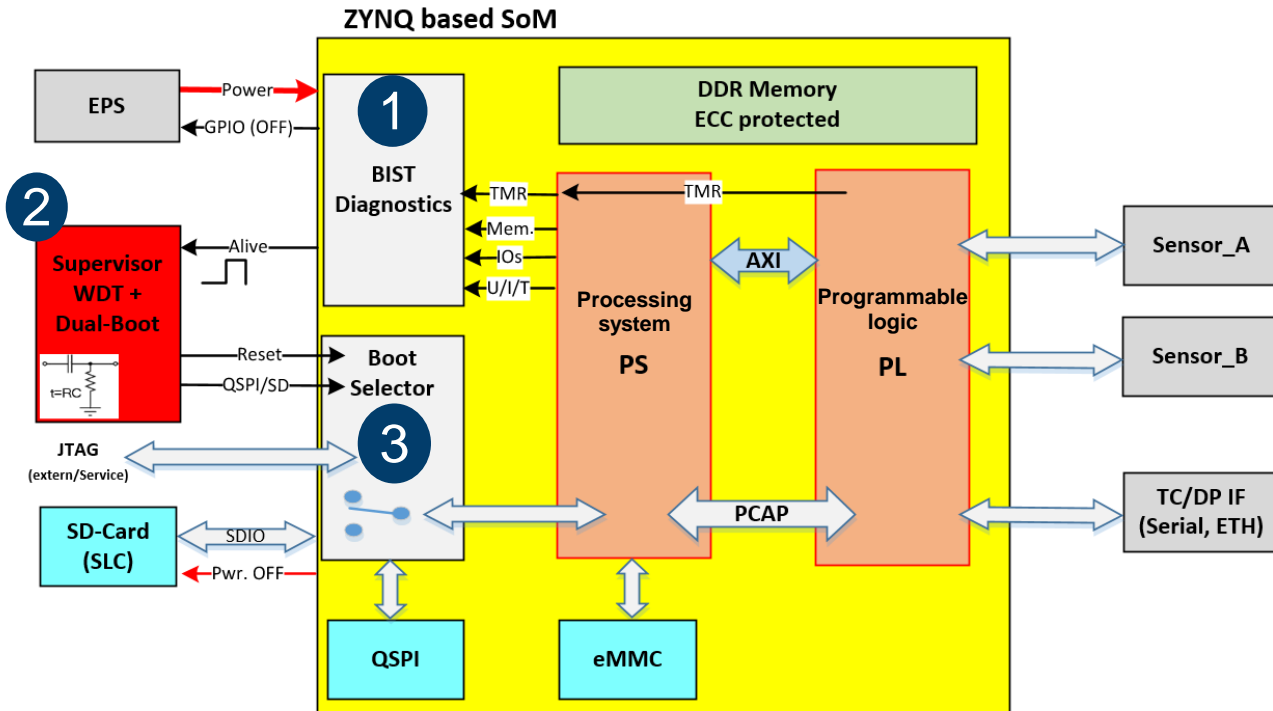
- SRAM-based XILINX System-on-Chip (SoC) architectures contains processing units (PS) and reconfigurable logic (PL)
- Mitigation techniques, protection circuits and **reconfiguration** for long-term measurements



Source: <https://shop.trenz-electronic.de>

video

## Blockdiagram



Firmware storage devices

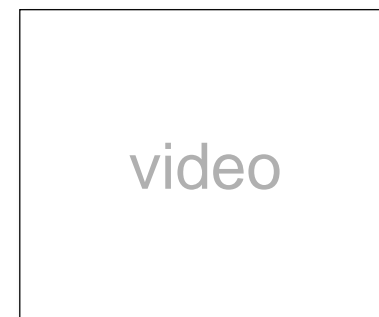
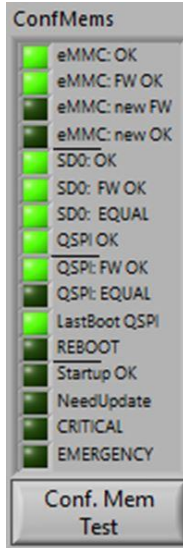
- QSPI nominal (primary) boot device
- SD-Card redundant (secondary) boot device
- eMMC Transfer memory and 'Golden image'

## Reconfiguration strategy

- Built-In-Self-Test (BIST):** Detection and monitoring of failure
  - Diagnostics for all vital functions
  - Classification in
    - Minor → Warning
    - Major errors → Reconfiguration
    - Critical situations → Shutdown

- Save reconfiguration**
  - on Software crash
  - compensate for SEU and SEFI induced errors
  - safe shutdown at SEL events

- Highly secured boot process**
  - Redundant boot devices
    - Automatic switch between Nominal/Redundant
  - 'Golden Image' in third device
  - BIST and automatic correction of invalid FW image



# SUPERVISOR CIRCUIT

## Simple watchdog IC with two functional blocks

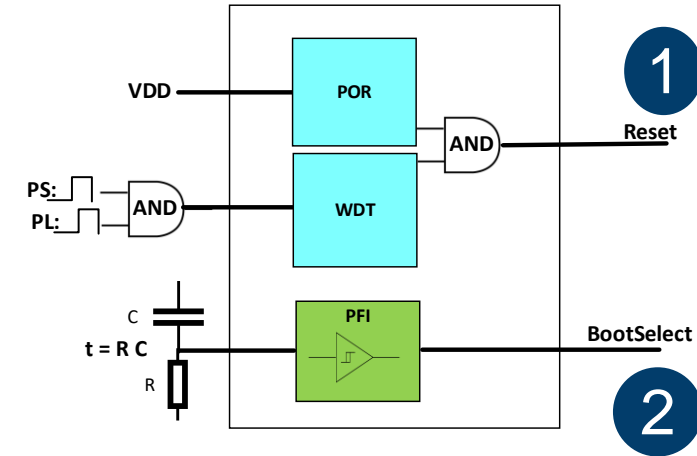


### 1 Triggering the Reconfiguration

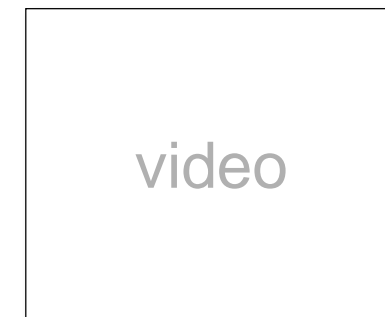
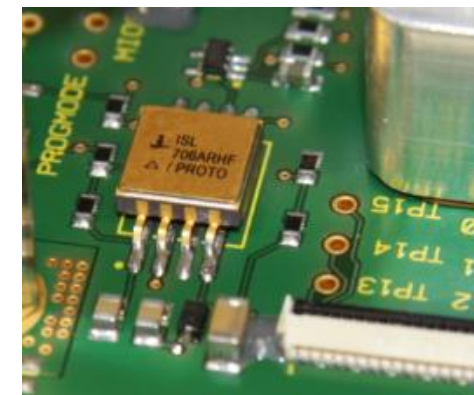
- 'alive' signal is a combined signal by software task at PS and logic block inside PL
- when PS or PL stops working (crash), WDT resets the system
- at major risks 'alive' trigger signal will be suppressed by BIST
  - SEU events occur inside TMR (PL)
  - Cyclic memory pattern checks fail (PS)
  - TM/TC and HK packages inconsistent
  - Error at peripheral interfaces (I<sup>2</sup>C, SPI, DMA)
  - Discrepancies in configuration memories

### 2 Dual Boot Functionality

- using time delay at PFI input during power up to start from nominal boot device
- corrupted configuration will force a reset **1** due to missing 'alive' signal and PFI output (BootSelect) has inverted after this time

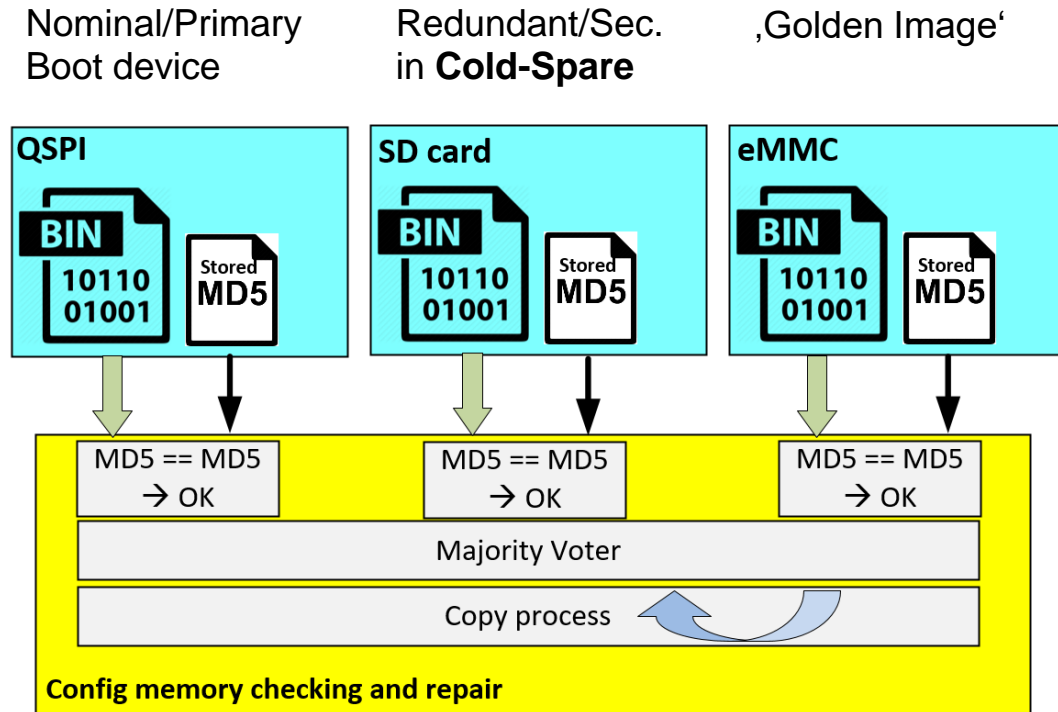


- ISL706ARH (5962R1121304VXC)
- QML qualified per MIL-PRF-38535
- High dose rate 100krad(Si)
- SEL LET<sub>TH</sub> 86MeV•cm<sup>2</sup>/mg



# FIRMWARE CHECK AND 'SELF-REPAIR'

## TMR like behavior of the three configuration memories



Each configuration memory holds the binary boot image and the correct MD5 hash tag in a separate file.

### 1) BIST

- At power-up time 'System-checker' process
- Firmware and stored MD5# are checked  
→ FW OK marker for each device
- MD5# tags are compared to each other's  
→ Discrepancy of memory content

### 2) Self-Repair, in case of a discrepancy

- consistent memory is copied to the faulty one

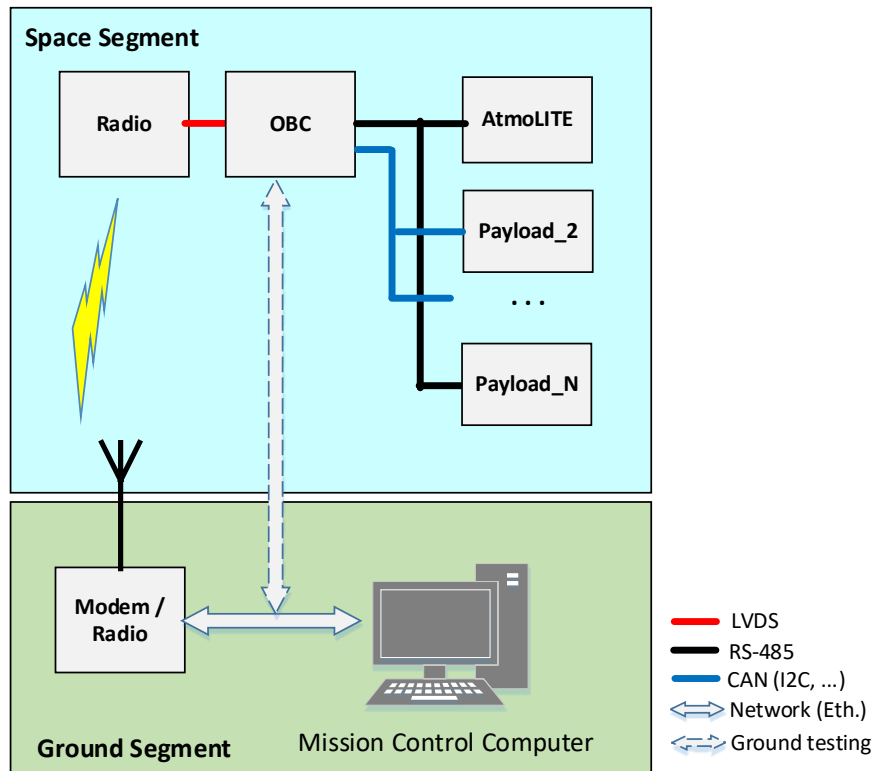
video

# IN-FLIGHT RECONFIGURATION



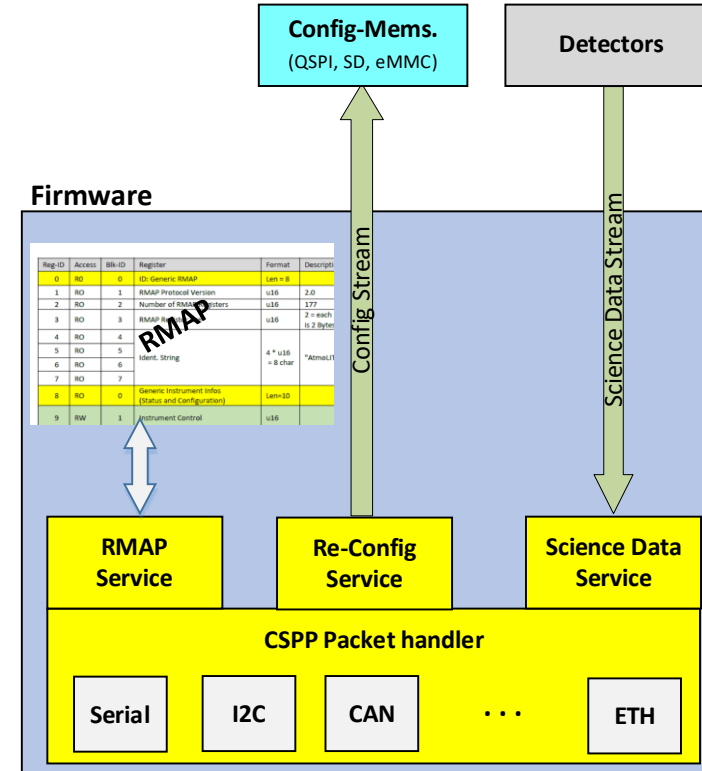
## Communication Concept

- OBC handles all ground communication via radio (S-, X- Band)
- Ground testing via direct network link
- Multiple physical interfaces



## CubeSat Space Packet Protocol\*(CSPP)

- CSPP supports multiple interfaces (physical layer)
- 16 Byte Header,
  - Protocol and Routing information
  - Parameter and Data block, CRC secured





# IN-FLIGHT FIRMWARE UPLOAD



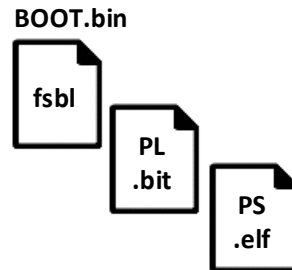
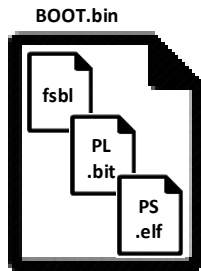
## Firmware

Firmware consists of **three** parts:

- First-Stage-Bootloader (fsbl) ~ 100 KB
- PL configuration bit stream (.bit) 1.8 ... 4 MB
- PS application code (.elf). ~ 1 MB (FreeRTOS)

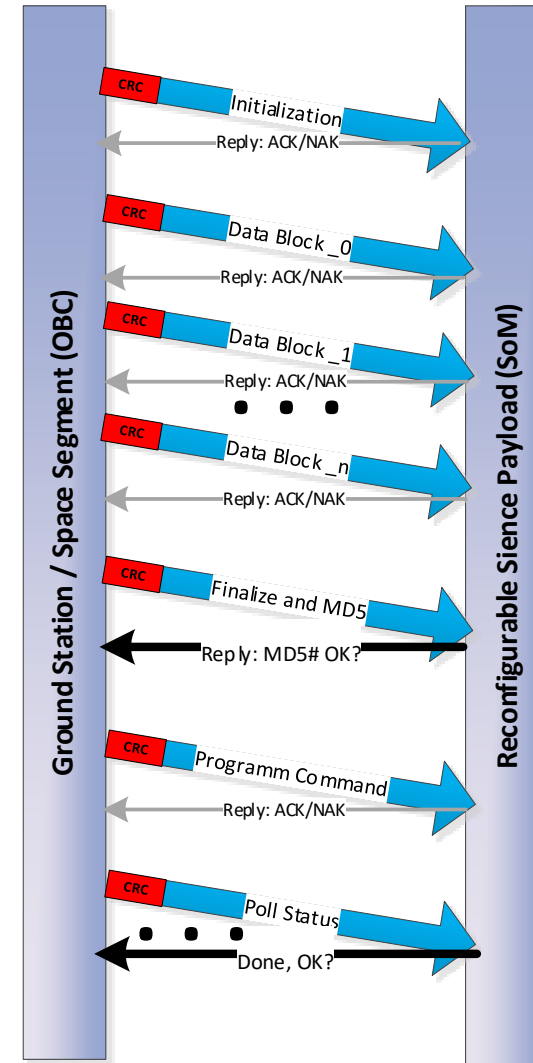
→ BOOT.BIN

or as single files



- Files can be compressed in Xilinx Vivado toolchain, to reduce uplink capacity

## Upload process



**Initialization** information  
- Total size of Configuration

**Upload** Data blocks:  
- block size in parameters  
- Data-CRC secured  
- Reply ACK/NAK  
- on NAK: resend block

**Validation**  
- Send MD5#  
- Generate local MD5#  
- Compare MD5's#  
- Reply ACK / NAK

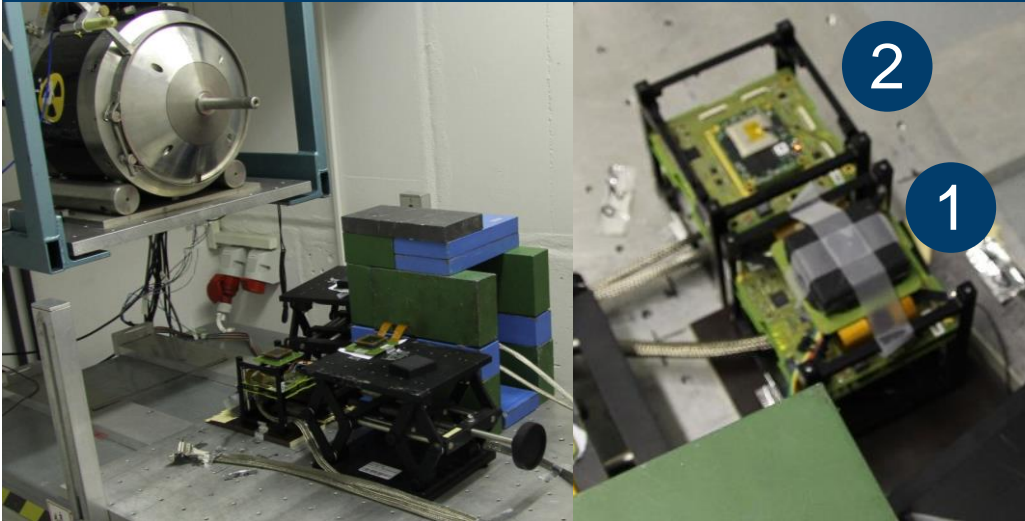
**Program** Operation

video

# FIRST IMPLEMENTATION RESULTS



## Radiation Test

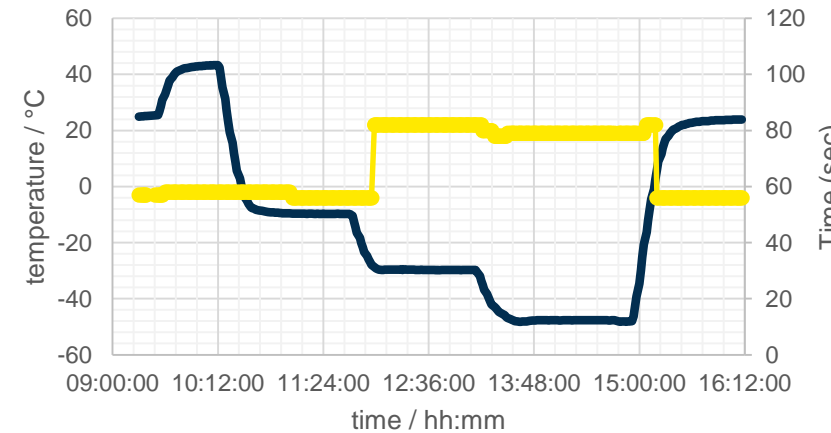


reconfiguration cycle	meas_time	dose rate in krad/h	TID / kRad	1 ZYNQ - 7000 TE720-ECC (S/N: 609088)			2 ULTRASCALE + TE820 (S/N: 527320)		
				QSPI	SD_Card	EMMC	QSPI	SD_Card	EMMC
1	18:44:00	1	0.00	pass	pass	pass	pass	pass	pass
2	19:40:00	1	0.93	pass	pass	pass	pass	pass	pass
3	22:05:00	1	3.35	pass	pass	pass	pass	pass	pass
4	23:50:00	1	5.10	pass	pass	pass	pass	pass	pass
5	05:30:00	1	10.76	pass	pass	pass	pass	pass	pass
6	08:30:00	1	13.76	pass	pass	pass			
7	09:15:00	1	14.51	fail	pass	pass			
8	10:50:00	0	14.51	fail	pass	pass			
9	12:14:00	3	18.71	fail	pass	pass			
10	12:29:00	3	19.40	fail	pass	pass			

## Thermal Cycling Tests



temperature cycling test

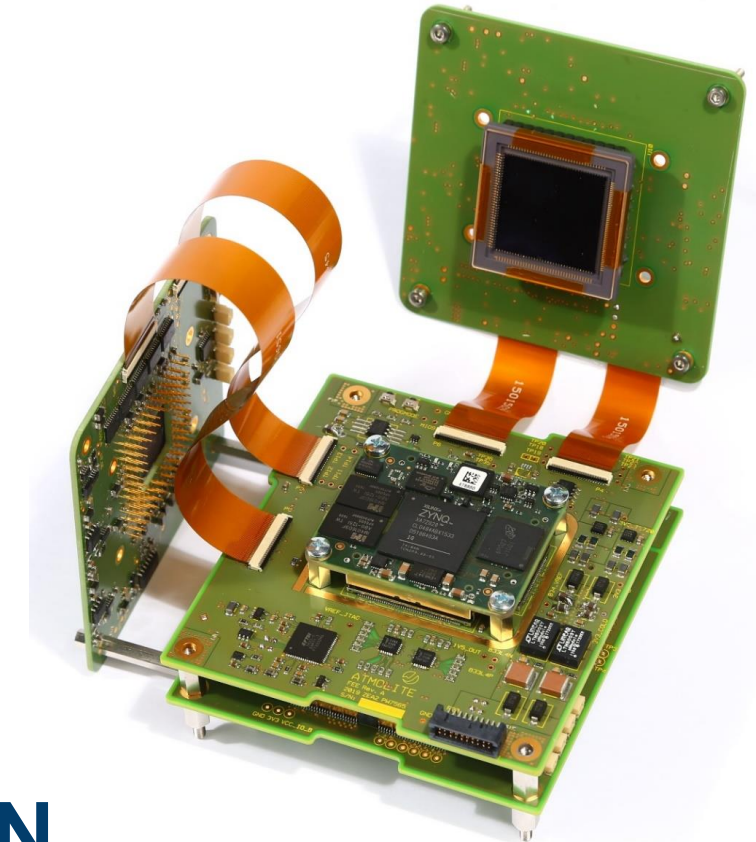


video

# SUMMARY



- Reconfiguration strategy using BIST classify hazards into different risk levels leads to interact on demand
- With additional memory devices available at SoM a highly secured boot process are demonstrated
- Dual boot functionality with a simple supervisor chip increases reliability
- Implementation of on-board firmware self check and repair is secured based on MD5 checksum
- In-flight reconfiguration using packet based protocol (CSP) is independent from physical layer interfaces (CAN, I<sup>2</sup>C, UART, LAN,...)
- Firmware can be partly uploaded and compressed to safe uplink time



## THANK YOU FOR YOUR ATTENTION

Please join the Q&A WEBINAR (Aug. 11th).  
Further information in conference proceeding paper (SSC21-VIII-08).

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